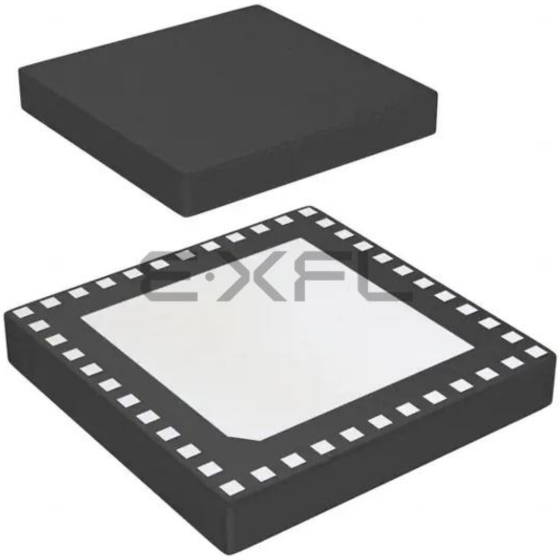
Microchip Technology - PIC32MX230F256D-I/TL Datasheet



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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	MIPS32® M4K™
Core Size	32-Bit Single-Core
Speed	40MHz
Connectivity	I²C, IrDA, LINbus, PMP, SPI, UART/USART, USB OTG
Peripherals	Brown-out Detect/Reset, DMA, I²S, POR, PWM, WDT
Number of I/O	33
Program Memory Size	256KB (256K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	16K x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 3.6V
Data Converters	A/D 13x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-VFTLA Exposed Pad
Supplier Device Package	44-VTLA (6x6)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic32mx230f256d-i-tl

TABLE 7: PIN NAMES FOR 36-PIN GENERAL PURPOSE DEVICES

36-PIN VTLA (TOP VIEW)(1,2,3,5)

PIC32MX110F016C
PIC32MX120F032C
PIC32MX130F064C
PIC32MX150F128C

36

1

Pin #	Full Pin Name	Pin #	Full Pin Name
1	AN4/C1INB/C2IND/RPB2/SDA2/CTED13/RB2	19	TDO/RPB9/SDA1/CTED4/PMD3/RB9
2	AN5/C1INA/C2INC/RTCC/RPB3/SCL2/RB3	20	RPC9/CTED7/RC9
3	PGED4(4)/AN6/RPC0/RC0	21	VSS
4	PGEC4(4)/AN7/RPC1/RC1	22	VCAP
5	VDD	23	VDD
6	VSS	24	PGED2/RPB10/CTED11/PMD2/RB10
7	OSC1/CLKI/RPA2/RA2	25	PGEC2/TMS/RPB11/PMD1/RB11
8	OSC2/CLKO/RPA3/PMA0/RA3	26	AN12/PMD0/RB12
9	SOSCI/RPB4/RB4	27	AN11/RPB13/CTPLS/PMRD/RB13
10	SOSCO/RPA4/T1CK/CTED9/PMA1/RA4	28	CVREFOUT/AN10/C3INB/RPB14/SCK1/CTED5/PMWR/RB14
11	RPC3/RC3	29	AN9/C3INA/RPB15/SCK2/CTED6/PMCS1/RB15
12	VSS	30	AVSS
13	VDD	31	AVDD
14	VDD	32	$\overline{\text{MCLR}}$
15	PGED3/RPB5/PMD7/RB5	33	VREF+/CVREF+/AN0/C3INC/RPA0/CTED1/RA0
16	PGEC3/RPB6/PMD6/RB6	34	VREF-/CVREF-/AN1/RPA1/CTED2/RA1
17	TDI/RPB7/CTED3/PMD5/INT0/RB7	35	PGED1/AN2/C1IND/C2INB/C3IND/RPB0/RB0
18	TCK/RPB8/SCL1/CTED10/PMD4/RB8	36	PGEC1/AN3/C1INC/C2INA/RPB1/CTED12/RB1

Note 1: The RPn pins can be used by remappable peripherals. See Table 1 for the available peripherals and **Section 11.3 "Peripheral Pin Select"** for restrictions.

2: Every I/O port pin (RAx-RCx) can be used as a change notification pin (CNAx-CNCx). See **Section 11.0 "I/O Ports"** for more information.

3: The metal plane at the bottom of the device is not connected to any pins and is recommended to be connected to VSS externally.

4: This pin function is not available on PIC32MX110F016C and PIC32MX120F032C devices.

5: Shaded pins are 5V tolerant.

TABLE 11: PIN NAMES FOR 44-PIN GENERAL PURPOSE DEVICES

44-PIN TQFP (TOP VIEW)(1,2,3,5)

PIC32MX110F016D
PIC32MX120F032D
PIC32MX130F064D
PIC32MX130F256D
PIC32MX150F128D
PIC32MX170F256D

44

1

Pin #	Full Pin Name	Pin #	Full Pin Name
1	RPB9/SDA1/CTED4/PMD3/RB9	23	AN4/C1INB/C2IND/RPB2/SDA2/CTED13/RB2
2	RPC6/PMA1/RC6	24	AN5/C1INA/C2INC/RTCC/RPB3/SCL2/RB3
3	RPC7/PMA0/RC7	25	AN6/RPC0/RC0
4	RPC8/PMA5/RC8	26	AN7/RPC1/RC1
5	RPC9/CTED7/PMA6/RC9	27	AN8/RPC2/PMA2/RC2
6	VSS	28	VDD
7	VCAP	29	VSS
8	PGED2/RPB10/CTED11/PMD2/RB10	30	OSC1/CLKI/RPA2/RA2
9	PGEC2/RPB11/PMD1/RB11	31	OSC2/CLKO/RPA3/RA3
10	AN12/PMD0/RB12	32	TDO/RPA8/PMA8/RA8
11	AN11/RPB13/CTPLS/PMRD/RB13	33	SOSCI/RPB4/RB4
12	PGED4(4)/TMS/PMA10/RA10	34	SOSCO/RPA4/T1CK/CTED9/RA4
13	PGEC4(4)/TCK/CTED8/PMA7/RA7	35	TDI/RPA9/PMA9/RA9
14	CVREFOUT/AN10/C3INB/RPB14/SCK1/CTED5/PMWR/RB14	36	RPC3/RC3
15	AN9/C3INA/RPB15/SCK2/CTED6/PMCS1/RB15	37	RPC4/PMA4/RC4
16	AVSS	38	RPC5/PMA3/RC5
17	AVDD	39	VSS
18	$\overline{\text{MCLR}}$	40	VDD
19	VREF+/CVREF+/AN0/C3INC/RPA0/CTED1/RA0	41	PGED3/RPB5/PMD7/RB5
20	VREF-/CVREF-/AN1/RPA1/CTED2/RA1	42	PGEC3/RPB6/PMD6/RB6
21	PGED1/AN2/C1IND/C2INB/C3IND/RPB0/RB0	43	RPB7/CTED3/PMD5/INT0/RB7
22	PGEC1/AN3/C1INC/C2INA/RPB1/CTED12/RB1	44	RPB8/SCL1/CTED10/PMD4/RB8

Note 1: The RPn pins can be used by remappable peripherals. See Table 1 for the available peripherals and **Section 11.3 "Peripheral Pin Select"** for restrictions.

2: Every I/O port pin (RAx-RCx) can be used as a change notification pin (CNAx-CNCx). See **Section 11.0 "I/O Ports"** for more information.

3: The metal plane at the bottom of the device is not connected to any pins and is recommended to be connected to VSS externally.

4: This pin function is not available on PIC32MX110F016D and PIC32MX120F032D devices.

5: Shaded pins are 5V tolerant.

Pull-up resistors, series diodes and capacitors on the PGECx and PGEDx pins are not recommended as they will interfere with the programmer/debugger communications to the device. If such discrete components are an application requirement, they should be removed from the circuit during programming and debugging. Alternatively, refer to the AC/DC characteristics and timing requirements information in the respective device Flash programming specification for information on capacitive loading limits and pin input voltage high (V_{IH}) and input low (V_{IL}) requirements.

Ensure that the "Communication Channel Select" (i.e., PGECx/PGEDx pins) programmed into the device matches the physical connections for the ICSP to MPLAB® ICD 3 or MPLAB REAL ICE™.

For more information on ICD 3 and REAL ICE connection requirements, refer to the following documents that are available on the Microchip web site:

- *"Using MPLAB® ICD 3"* (poster) (DS50001765)
- *"MPLAB® ICD 3 Design Advisory"* (DS50001764)
- *"MPLAB® REAL ICE™ In-Circuit Debugger User's Guide" (*DS50001616)
- *"Using MPLAB® REAL ICE™ Emulator"* (poster) (DS50001749)

2.6 JTAG

The TMS, TDO, TDI and TCK pins are used for testing and debugging according to the Joint Test Action Group (JTAG) standard. It is recommended to keep the trace length between the JTAG connector and the JTAG pins on the device as short as possible. If the JTAG connector is expected to experience an ESD event, a series resistor is recommended with the value in the range of a few tens of Ohms, not to exceed 100 Ohms.

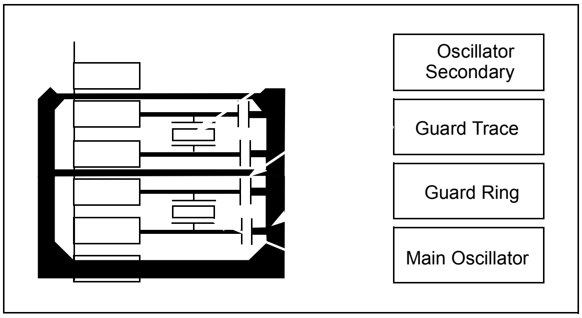
Pull-up resistors, series diodes and capacitors on the TMS, TDO, TDI and TCK pins are not recommended as they will interfere with the programmer/debugger communications to the device. If such discrete components are an application requirement, they should be removed from the circuit during programming and debugging. Alternatively, refer to the AC/DC characteristics and timing requirements information in the respective device Flash programming specification for information on capacitive loading limits and pin input voltage high (V_{IH}) and input low (V_{IL}) requirements.

2.7 External Oscillator Pins

Many MCUs have options for at least two oscillators: a high-frequency primary oscillator and a low-frequency secondary oscillator (refer to **Section 8.0 "Oscillator Configuration"** for details).

The oscillator circuit should be placed on the same side of the board as the device. Also, place the oscillator circuit close to the respective oscillator pins, not exceeding one-half inch (12 mm) distance between them. The load capacitors should be placed next to the oscillator itself, on the same side of the board. Use a grounded copper pour around the oscillator circuit to isolate them from surrounding circuits. The grounded copper pour should be routed directly to the MCU ground. Do not run any signal traces or power traces inside the ground pour. Also, if using a two-sided board, avoid any traces on the other side of the board where the crystal is placed. A suggested layout is illustrated in Figure 2-3.

FIGURE 2-3: SUGGESTED OSCILLATOR CIRCUIT PLACEMENT

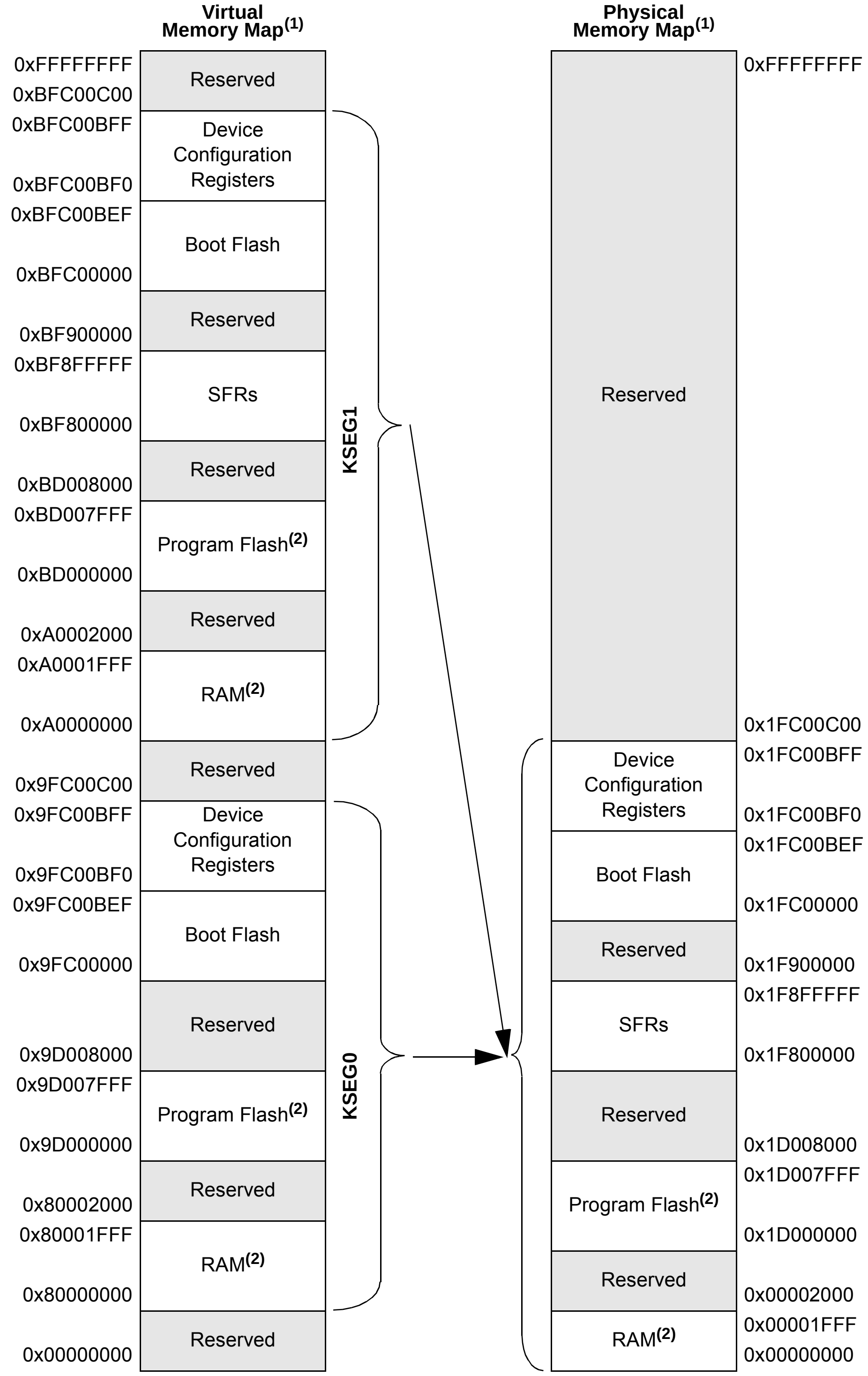


2.8 Unused I/Os

Unused I/O pins should not be allowed to float as inputs. They can be configured as outputs and driven to a logic-low state.

Alternatively, inputs can be reserved by connecting the pin to V_{SS} through a 1k to 10k resistor and configuring the pin as an input.

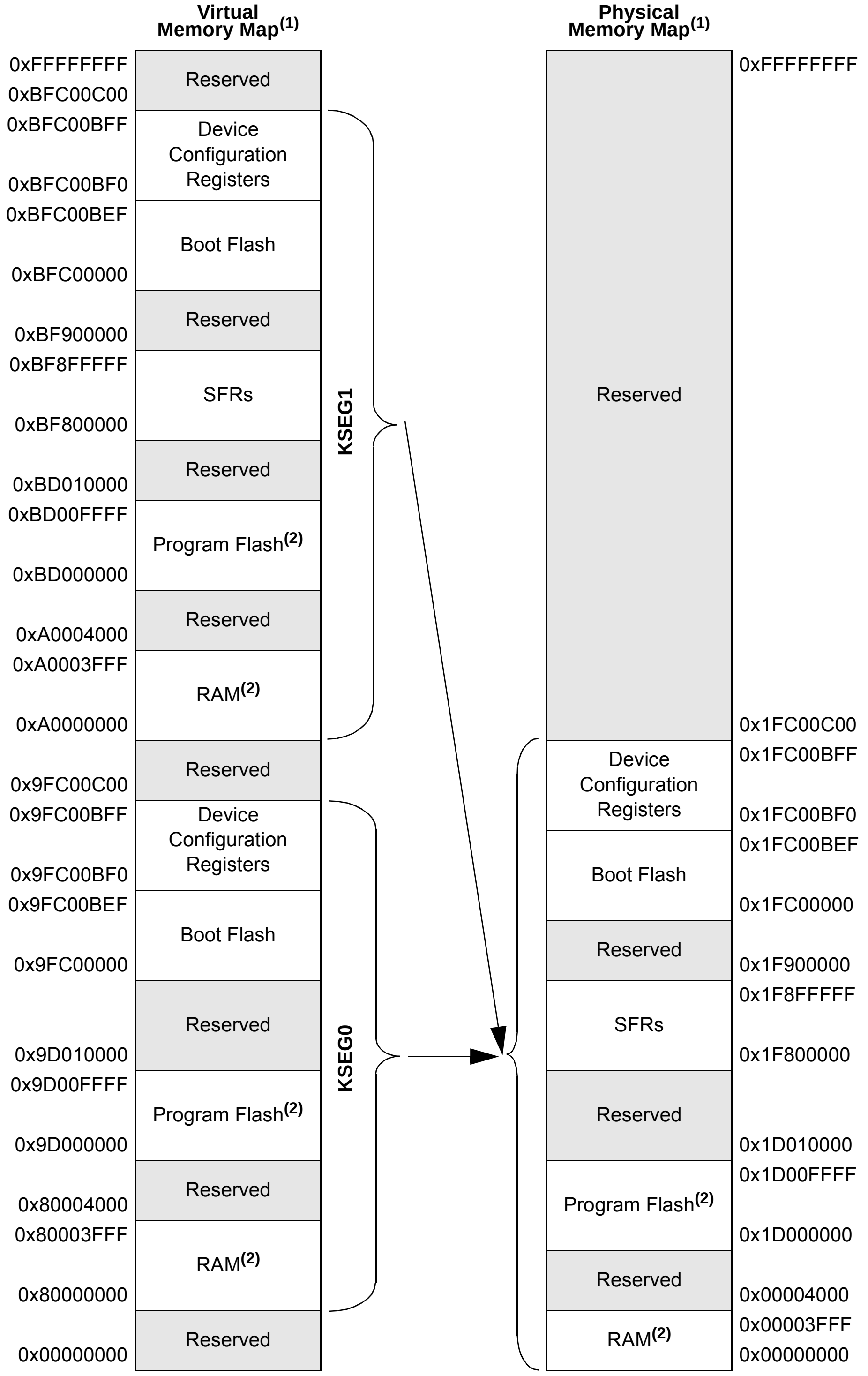
FIGURE 4-2: MEMORY MAP ON RESET FOR PIC32MX120/220 DEVICES (8 KB RAM, 32 KB FLASH)



Note 1: Memory areas are not shown to scale.

2: The size of this memory region is programmable (see **Section 3. "Memory Organization"** (DS60001115) in the *"PIC32 Family Reference Manual"*) and can be changed by initialization code provided by end-user development tools (refer to the specific development tool documentation for information).

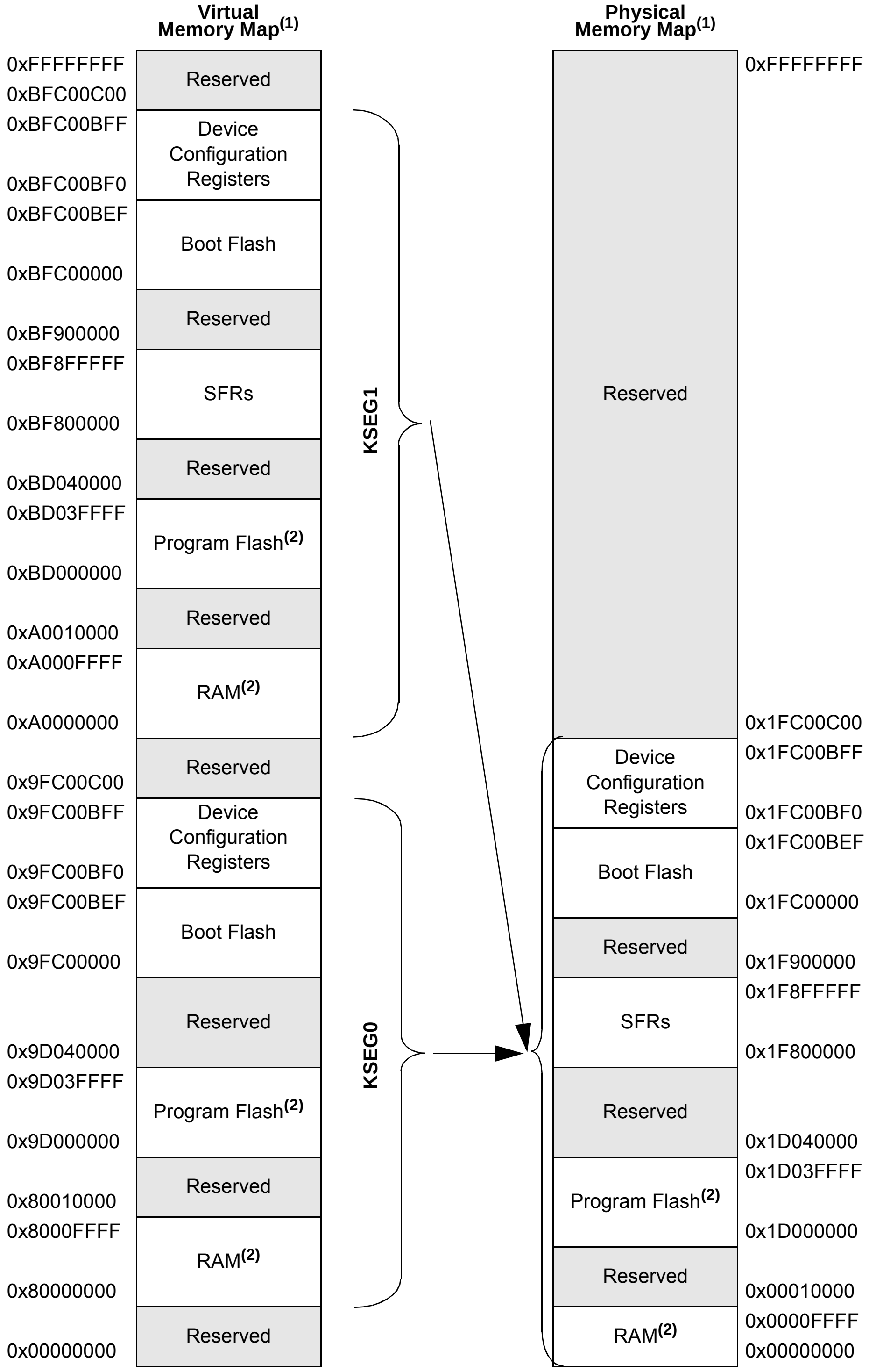
FIGURE 4-3: MEMORY MAP ON RESET FOR PIC32MX130/230 DEVICES (16 KB RAM, 64 KB FLASH)



Note 1: Memory areas are not shown to scale.

2: The size of this memory region is programmable (see **Section 3. "Memory Organization"** (DS60001115) in the *"PIC32 Family Reference Manual"*) and can be changed by initialization code provided by end-user development tools (refer to the specific development tool documentation for information).

FIGURE 4-5: MEMORY MAP ON RESET FOR PIC32MX170/270 DEVICES (64 KB RAM, 256 KB FLASH)



Note 1: Memory areas are not shown to scale.

2: The size of this memory region is programmable (see **Section 3. “Memory Organization”** (DS60001115) in the *“PIC32 Family Reference Manual”*) and can be changed by initialization code provided by end-user development tools (refer to the specific development tool documentation for information).

REGISTER 7-6: IPCx: INTERRUPT PRIORITY CONTROL REGISTER (CONTINUED)

bit 9-8	**IS01<1:0>:** Interrupt Subpriority bits `11` = Interrupt subpriority is 3 `10` = Interrupt subpriority is 2 `01` = Interrupt subpriority is 1 `00` = Interrupt subpriority is 0
bit 7-5	**Unimplemented:** Read as ‘`0`’
bit 4-2	**IP00<2:0>:** Interrupt Priority bits `111` = Interrupt priority is 7 • • • `010` = Interrupt priority is 2 `001` = Interrupt priority is 1 `000` = Interrupt is disabled
bit 1-0	**IS00<1:0>:** Interrupt Subpriority bits `11` = Interrupt subpriority is 3 `10` = Interrupt subpriority is 2 `01` = Interrupt subpriority is 1 `00` = Interrupt subpriority is 0

Note: This register represents a generic definition of the IPCx register. Refer to Table 7-1 for the exact bit definitions.

REGISTER 9-9: DCHxINT: DMA CHANNEL ‘x’ INTERRUPT CONTROL REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	CHSDIE	CHSHIE	CHDDIE	CHDHIE	CHBCIE	CHCCIE	CHTAIE	CHERIE
15:8	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	CHSDIF	CHSHIF	CHDDIF	CHDHIF	CHBCIF	CHCCIF	CHTAIF	CHERIF

Legend:

R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 31-24 **Unimplemented:** Read as ‘0’

bit 23 **CHSDIE:** Channel Source Done Interrupt Enable bit
1 = Interrupt is enabled
0 = Interrupt is disabled

bit 22 **CHSHIE:** Channel Source Half Empty Interrupt Enable bit
1 = Interrupt is enabled
0 = Interrupt is disabled

bit 21 **CHDDIE:** Channel Destination Done Interrupt Enable bit
1 = Interrupt is enabled
0 = Interrupt is disabled

bit 20 **CHDHIE:** Channel Destination Half Full Interrupt Enable bit
1 = Interrupt is enabled
0 = Interrupt is disabled

bit 19 **CHBCIE:** Channel Block Transfer Complete Interrupt Enable bit
1 = Interrupt is enabled
0 = Interrupt is disabled

bit 18 **CHCCIE:** Channel Cell Transfer Complete Interrupt Enable bit
1 = Interrupt is enabled
0 = Interrupt is disabled

bit 17 **CHTAIE:** Channel Transfer Abort Interrupt Enable bit
1 = Interrupt is enabled
0 = Interrupt is disabled

bit 16 **CHERIE:** Channel Address Error Interrupt Enable bit
1 = Interrupt is enabled
0 = Interrupt is disabled

bit 15-8 **Unimplemented:** Read as ‘0’

bit 7 **CHSDIF:** Channel Source Done Interrupt Flag bit
1 = Channel Source Pointer has reached end of source (CHSPTR = CHSSIZ)
0 = No interrupt is pending

bit 6 **CHSHIF:** Channel Source Half Empty Interrupt Flag bit
1 = Channel Source Pointer has reached midpoint of source (CHSPTR = CHSSIZ/2)
0 = No interrupt is pending

bit 5 **CHDDIF:** Channel Destination Done Interrupt Flag bit
1 = Channel Destination Pointer has reached end of destination (CHDPTR = CHDSIZ)
0 = No interrupt is pending

13.0 TIMER2/3, TIMER4/5

Note: This data sheet summarizes the features of the PIC32MX1XX/2XX 28/36/44-pin Family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 14. "Timers"** (DS60001105), which is available from the *Documentation > Reference Manual* section of the Microchip PIC32 web site (www.microchip.com/pic32).

This family of PIC32 devices features four synchronous 16-bit timers (default) that can operate as a free-running interval timer for various timing applications and counting external events. The following modes are supported:

- Synchronous internal 16-bit timer
- Synchronous internal 16-bit gated timer
- Synchronous external 16-bit timer

Two 32-bit synchronous timers are available by combining Timer2 with Timer3 and Timer4 with Timer5. The 32-bit timers can operate in three modes:

- Synchronous internal 32-bit timer
- Synchronous internal 32-bit gated timer
- Synchronous external 32-bit timer

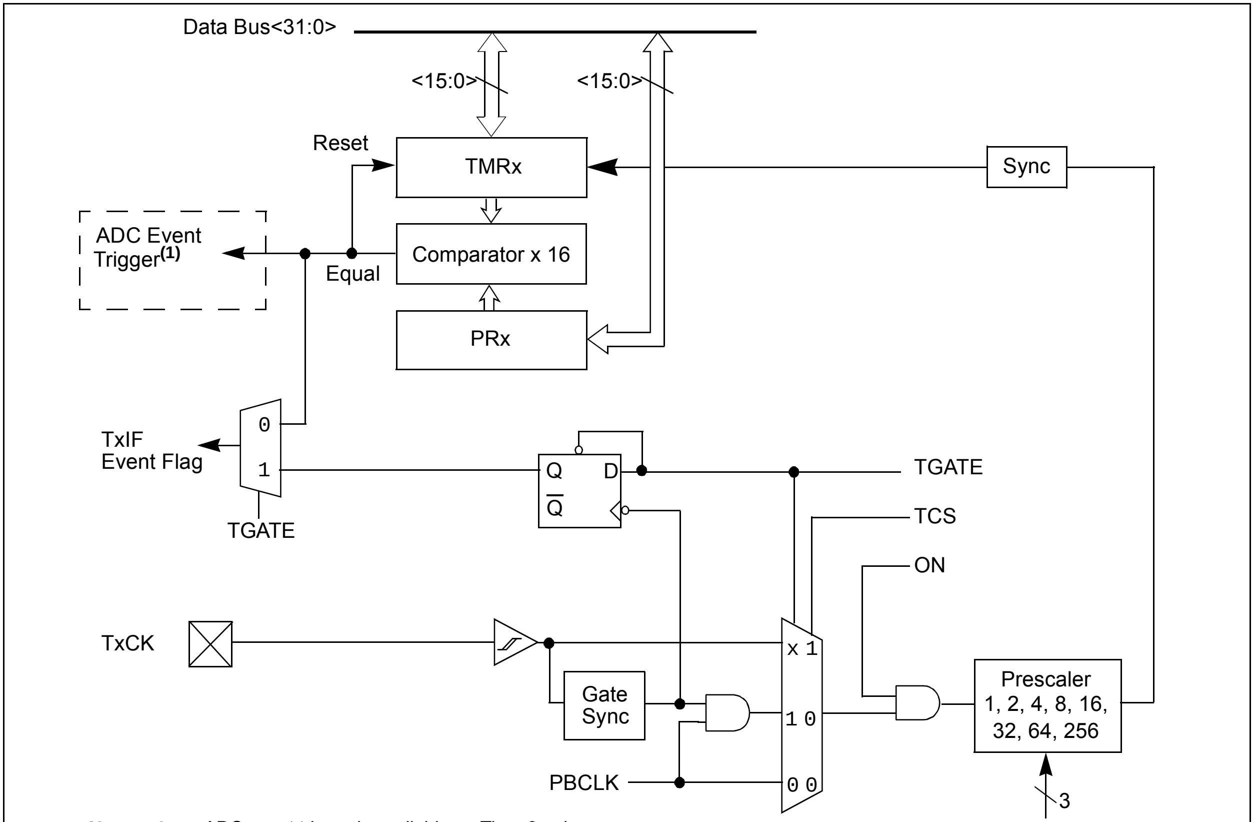
Note: In this chapter, references to registers, TxCON, TMRx and PRx, use 'x' to represent Timer2 through Timer5 in 16-bit modes. In 32-bit modes, 'x' represents Timer2 or Timer4 and 'y' represents Timer3 or Timer5.

13.1 Additional Supported Features

- Selectable clock prescaler
- Timers operational during CPU idle
- Time base for Input Capture and Output Compare modules (Timer2 and Timer3 only)
- ADC event trigger (Timer3 in 16-bit mode, Timer2/3 in 32-bit mode)
- Fast bit manipulation using CLR, SET and INV registers

Figure 13-1 and Figure 13-2 illustrate block diagrams of Timer2/3 and Timer4/5.

FIGURE 13-1: TIMER2-TIMER5 BLOCK DIAGRAM (16-BIT)



Note 1: ADC event trigger is available on Timer3 only.

18.0 INTER-INTEGRATED CIRCUIT (I^2C)

Note: This data sheet summarizes the features of the PIC32MX1XX/2XX 28/36/44-pin Family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 24. “Inter-Integrated Circuit (I^2C)”** (DS60001116), which is available from the *Documentation* > *Reference Manual* section of the Microchip PIC32 web site (www.microchip.com/pic32).

The I^2C module provides complete hardware support for both Slave and Multi-Master modes of the I^2C serial communication standard. Figure 18-1 illustrates the I^2C module block diagram.

Each I^2C module has a 2-pin interface: the SCLx pin is clock and the SDAx pin is data.

Each I^2C module offers the following key features:

- I^2C interface supporting both master and slave operation
- I^2C Slave mode supports 7-bit and 10-bit addressing
- I^2C Master mode supports 7-bit and 10-bit addressing
- I^2C port allows bidirectional transfers between master and slaves
- Serial clock synchronization for the I^2C port can be used as a handshake mechanism to suspend and resume serial transfer (SCLREL control)
- I^2C supports multi-master operation; detects bus collision and arbitrates accordingly
- Provides support for address bit masking

Figure 19-2 and Figure 19-3 illustrate typical receive and transmit timing for the UART module.

FIGURE 19-2: UART RECEPTION

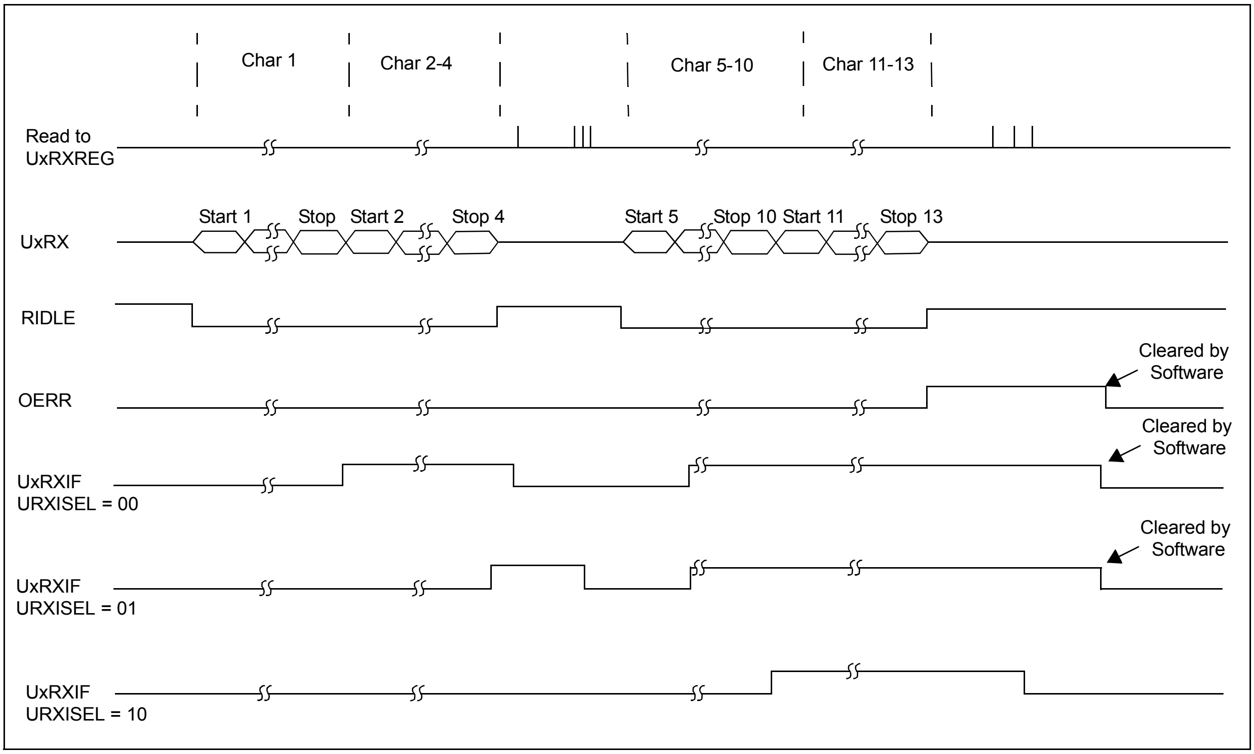
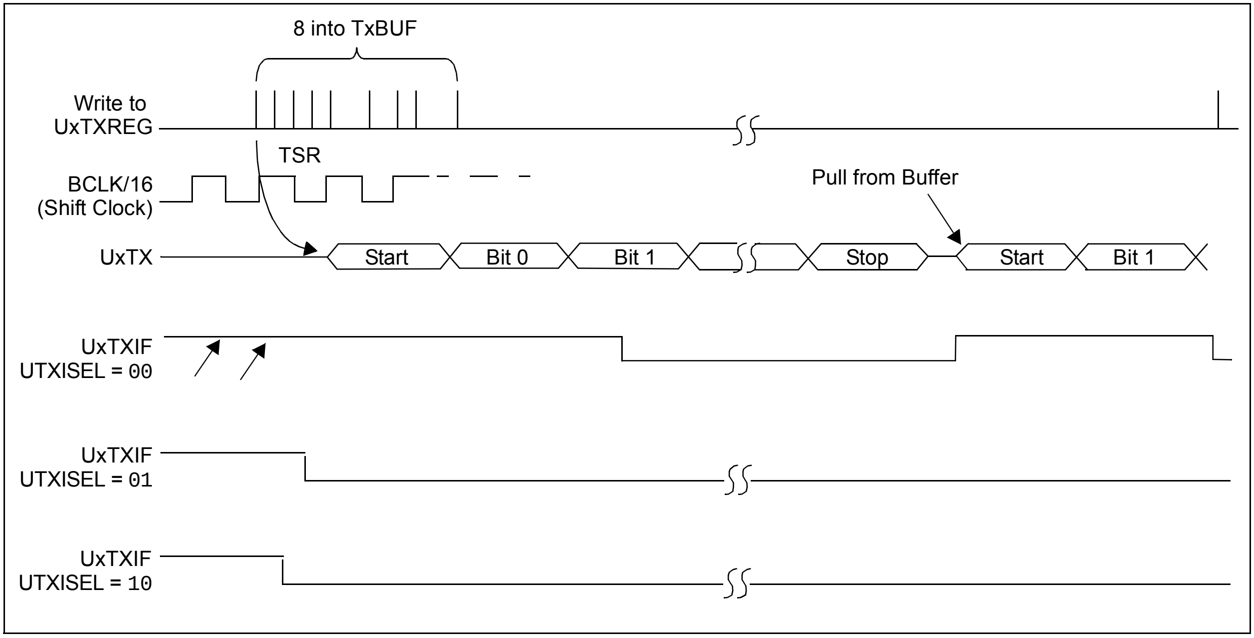


FIGURE 19-3: TRANSMISSION (8-BIT OR 9-BIT DATA)



NOTES:

25.1 CTMU Control Registers

TABLE 25-1: CTMU REGISTER MAP

Virtual Address (BF80_#)	Register Name(1)	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
A200	CTMUCON	31:16	EDG1MOD	EDG1POL	EDG1SEL<3:0>				EDG2STAT	EDG1STAT	EDG2MOD	EDG2POL	EDG2SEL<3:0>				—	—	`0000`
		15:0	ON	—	CTMUSIDL	TGEN	EDGEN	EDGSEQEN	IDISSEN	CTTRIG	ITRIM<5:0>						IRNG<1:0>		`0000`

Legend: x = unknown value on Reset; — = unimplemented, read as ‘`0`’. Reset values are shown in hexadecimal.

Note 1: All registers in this table have corresponding CLR, SET and INV registers at its virtual address, plus an offset of 0x4, 0x8 and 0xC, respectively. See **Section 11.2 “CLR, SET and INV Registers”** for more information.

REGISTER 27-2: DEVCFG1: DEVICE CONFIGURATION WORD 1 (CONTINUED)

bit 15-14 **FCKSM<1:0>:** Clock Switching and Monitor Selection Configuration bits

`1x` = Clock switching is disabled, Fail-Safe Clock Monitor is disabled
`01` = Clock switching is enabled, Fail-Safe Clock Monitor is disabled
`00` = Clock switching is enabled, Fail-Safe Clock Monitor is enabled

bit 13-12 **FPBDIV<1:0>:** Peripheral Bus Clock Divisor Default Value bits

`11` = PBCLK is SYSCLK divided by 8
`10` = PBCLK is SYSCLK divided by 4
`01` = PBCLK is SYSCLK divided by 2
`00` = PBCLK is SYSCLK divided by 1

bit 11 **Reserved:** Write ‘`1`’

bit 10 **OSCIOFNC:** CLKO Enable Configuration bit

`1` = CLKO output disabled
`0` = CLKO output signal active on the OSCO pin; Primary Oscillator must be disabled or configured for the External Clock mode (EC) for the CLKO to be active (POSCMOD<1:0> = `11` or `00`)

bit 9-8 **POSCMOD<1:0>:** Primary Oscillator Configuration bits

`11` = Primary Oscillator is disabled
`10` = HS Oscillator mode is selected
`01` = XT Oscillator mode is selected
`00` = External Clock mode is selected

bit 7 **IESO:** Internal External Switchover bit

`1` = Internal External Switchover mode is enabled (Two-Speed Start-up is enabled)
`0` = Internal External Switchover mode is disabled (Two-Speed Start-up is disabled)

bit 6 **Reserved:** Write ‘`1`’

bit 5 **FSOSCEN:** Secondary Oscillator Enable bit

`1` = Enable Secondary Oscillator
`0` = Disable Secondary Oscillator

bit 4-3 **Reserved:** Write ‘`1`’

bit 2-0 **FNOSC<2:0>:** Oscillator Selection bits

`111` = Fast RC Oscillator with divide-by-N (FRCDIV)
`110` = FRCDIV16 Fast RC Oscillator with fixed divide-by-16 postscaler
`101` = Low-Power RC Oscillator (LPRC)
`100` = Secondary Oscillator (SOSC)
`011` = Primary Oscillator (POSC) with PLL module (XT+PLL, HS+PLL, EC+PLL)
`010` = Primary Oscillator (XT, HS, EC)(1)
`001` = Fast RC Oscillator with divide-by-N with PLL module (FRCDIV+PLL)
`000` = Fast RC Oscillator (FRC)

Note 1: Do not disable the POSC (POSCMOD = `11`) when using this oscillator source.

30.0 ELECTRICAL CHARACTERISTICS

This section provides an overview of the PIC32MX1XX/2XX 28/36/44-pin Family electrical characteristics for devices that operate at 40 MHz. Refer to **Section 31.0 “50 MHz Electrical Characteristics”** for additional specifications for operations at higher frequency. Additional information will be provided in future revisions of this document as it becomes available.

Absolute maximum ratings for the PIC32MX1XX/2XX 28/36/44-pin Family devices are listed below. Exposure to these maximum rating conditions for extended periods may affect device reliability. Functional operation of the device at these or any other conditions, above the parameters indicated in the operation listings of this specification, is not implied.

Absolute Maximum Ratings

(See Note 1)

Ambient temperature under bias	-40°C to +105°C
Storage temperature	-65°C to +150°C
Voltage on VDD with respect to VSS	-0.3V to +4.0V
Voltage on any pin that is not 5V tolerant, with respect to VSS **(Note 3)**	-0.3V to (VDD + 0.3V)
Voltage on any 5V tolerant pin with respect to VSS when VDD ≥ 2.3V **(Note 3)**	-0.3V to +5.5V
Voltage on any 5V tolerant pin with respect to VSS when VDD < 2.3V **(Note 3)**	-0.3V to +3.6V
Voltage on D+ or D- pin with respect to VUSB3V3	-0.3V to (VUSB3V3 + 0.3V)
Voltage on VBUS with respect to VSS	-0.3V to +5.5V
Maximum current out of VSS pin(s)	300 mA
Maximum current into VDD pin(s) **(Note 2)**	300 mA
Maximum output current sunk by any I/O pin	15 mA
Maximum output current sourced by any I/O pin	15 mA
Maximum current sunk by all ports	200 mA
Maximum current sourced by all ports **(Note 2)**	200 mA

Note 1: Stresses above those listed under **“Absolute Maximum Ratings”** may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions, above those indicated in the operation listings of this specification, is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

2: Maximum allowable current is a function of device maximum power dissipation (see Table 30-2).

3: See the **“Pin Diagrams”** section for the 5V tolerant pins.

TABLE 30-8: DC CHARACTERISTICS: I/O PIN INPUT SPECIFICATIONS

DC CHARACTERISTICS			**Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics**	**Min.**	**Typical(1)**	**Max.**	**Units**	**Conditions**
	VIL	**Input Low Voltage**					
DI10		I/O Pins with PMP	VSS	—	0.15 VDD	V	
		I/O Pins	VSS	—	0.2 VDD	V	
DI18		SDAx, SCLx	VSS	—	0.3 VDD	V	SMBus disabled **(Note 4)**
DI19		SDAx, SCLx	VSS	—	0.8	V	SMBus enabled **(Note 4)**
	VIH	**Input High Voltage**					
DI20		I/O Pins not 5V-tolerant(5)	0.65 VDD	—	VDD	V	**(Note 4,6)**
		I/O Pins 5V-tolerant with PMP(5)	0.25 VDD + 0.8V	—	5.5	V	**(Note 4,6)**
		I/O Pins 5V-tolerant(5)	0.65 VDD	—	5.5	V	
DI28		SDAx, SCLx	0.65 VDD	—	5.5	V	SMBus disabled **(Note 4,6)**
DI29		SDAx, SCLx	2.1	—	5.5	V	SMBus enabled, 2.3V ≤ VPIN ≤ 5.5 **(Note 4,6)**
DI30	ICNPU	**Change Notification Pull-up Current**	—	—	-50	µA	VDD = 3.3V, VPIN = VSS **(Note 3,6)**
DI31	ICNPD	**Change Notification Pull-down Current(4)**	—	—	-50	µA	VDD = 3.3V, VPIN = VDD
	IIL	**Input Leakage Current (Note 3)**					
DI50		I/O Ports	—	—	±1	µA	VSS ≤ VPIN ≤ VDD, Pin at high-impedance
DI51		Analog Input Pins	—	—	±1	µA	VSS ≤ VPIN ≤ VDD, Pin at high-impedance
DI55		$\overline{\text{MCLR}}$(2)	—	—	±1	µA	VSS ≤ VPIN ≤ VDD
DI56		OSC1	—	—	±1	µA	VSS ≤ VPIN ≤ VDD, XT and HS modes

Note 1: Data in “Typical” column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

2: The leakage current on the $\overline{\text{MCLR}}$ pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as current sourced by the pin.

4: This parameter is characterized, but not tested in manufacturing.

5: See the **“Pin Diagrams”** section for the 5V-tolerant pins.

6: The VIH specifications are only in relation to externally applied inputs, and not with respect to the user-selectable internal pull-ups. External open drain input signals utilizing the internal pull-ups of the PIC32 device are guaranteed to be recognized only as a logic “high” internally to the PIC32 device, provided that the external load does not exceed the minimum value of ICNPU. For External “input” logic inputs that require a pull-up source, to guarantee the minimum VIH of those components, it is recommended to use an external pull-up resistor rather than the internal pull-ups of the PIC32 device.

TABLE 30-39: PARALLEL MASTER PORT WRITE TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics(1)**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
PM11	TWR	PMWR Pulse Width	—	1 TPB	—	—	—
PM12	TDVSU	Data Out Valid before PMWR or PMENB goes Inactive (data setup time)	—	2 TPB	—	—	—
PM13	TDVHOLD	PMWR or PMEMB Invalid to Data Out Invalid (data hold time)	—	1 TPB	—	—	—

Note 1: These parameters are characterized, but not tested in manufacturing.

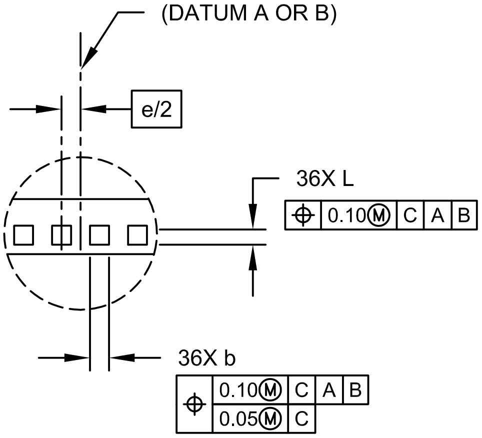
TABLE 30-40: OTG ELECTRICAL SPECIFICATIONS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics(1)**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
USB313	VUSB3V3	USB Voltage	3.0	—	3.6	V	Voltage on VUSB3V3 must be in this range for proper USB operation
USB315	VILUSB	Input Low Voltage for USB Buffer	—	—	0.8	V	—
USB316	VIHUSB	Input High Voltage for USB Buffer	2.0	—	—	V	—
USB318	VDIFS	Differential Input Sensitivity	—	—	0.2	V	The difference between D+ and D- must exceed this value while VCM is met
USB319	VCM	Differential Common Mode Range	0.8	—	2.5	V	—
USB320	ZOUT	Driver Output Impedance	28.0	—	44.0	Ω	—
USB321	VOL	Voltage Output Low	0.0	—	0.3	V	1.425 kΩ load connected to VUSB3V3
USB322	VOH	Voltage Output High	2.8	—	3.6	V	1.425 kΩ load connected to ground

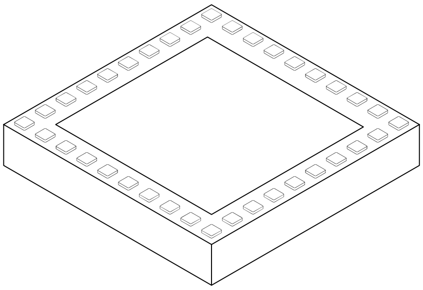
Note 1: These parameters are characterized, but not tested in manufacturing.

36-Terminal Very Thin Thermal Leadless Array Package (TL) – 5x5x0.9 mm Body with Exposed Pad [VTLA]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



DETAIL A



Dimension Limits	Units	MILLIMETERS		
		MIN	NOM	MAX
Number of Pins	N	36		
Number of Pins per Side	ND	10		
Number of Pins per Side	NE	8		
Pitch	e	0.50 BSC		
Overall Height	A	0.80	0.90	1.00
Standoff	A1	0.025	-	0.075
Overall Width	E	5.00 BSC		
Exposed Pad Width	E2	3.60	3.75	3.90
Overall Length	D	5.00 BSC		
Exposed Pad Length	D2	3.60	3.75	3.90
Contact Width	b	0.20	0.25	0.30
Contact Length	L	0.20	0.25	0.30
Contact-to-Exposed Pad	K	0.20	-	-

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated.
3. Dimensioning and tolerancing per ASME Y14.5M.
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.
   REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-187C Sheet 2 of 2

Revision E (October 2012)

All singular pin diagram occurrences of CVREF were changed to: CVREFOUT. In addition, minor text and formatting changes were incorporated throughout the document.

All major changes are referenced by their respective section in Table A-4.

TABLE A-4: MAJOR SECTION UPDATES

Section	Update Description
“32-bit Microcontrollers (up to 128 KB Flash and 32 KB SRAM) with Audio and Graphics Interfaces, USB, and Advanced Analog”	Updated the following feature sections: • **“Operating Conditions”** • **“Communication Interfaces”**
2.0 “Guidelines for Getting Started with 32-bit MCUs”	Removed Section 2.8 “Configuration of Analog and Digital Pins During ICSP Operations”.
3.0 “CPU”	Removed references to GPR shadow registers in **3.1 “Features”** and **3.2.1 “Execution Unit”**.
4.0 “Memory Organization”	Updated the BRG bit range in the SPI1 and SPI2 Register Map (see Table 4-8). Added the PWP<6> bit to the Device Configuration Word Summary (see Table 4-17).
5.0 “Flash Program Memory”	Added a note with Flash page size and row size information.
7.0 “Interrupt Controller”	Updated the TPC<2:0> bit definitions (see Register 7-1). Updated the IPTMR<31:0> bit definition (see Register 7-3).
8.0 “Oscillator Configuration”	Updated the PIC32MX1XX/2XX Family Clock Diagram (see Figure 8-1). Updated the RODIV<14:0> bit definitions (see Register 8-3).
10.0 “USB On-The-Go (OTG)”	Updated the Notes in the USB Interface Diagram (see Figure 10-1).
18.0 “Universal Asynchronous Receiver Transmitter (UART)”	Updated the baud rate range in the list of primary features.
26.0 “Special Features”	Added the PWP<6> bit to the Device Configuration Word 0 (see Register 26-1).
29.0 “Electrical Characteristics”	Added Note 1 to Operating MIPS vs. Voltage (see Table 29-1). Added Note 2 to DC Temperature and Voltage Specifications (see Table 29-4). Updated the Conditions for parameter DC25 in DC Characteristics: Operating Current (IDD) (see Table 29-5). Added Note 2 to Electrical Characteristics: BOR (see Table 29-10). Added Note 4 to Comparator Specifications (see Table 29-12). Added Note 5 to ADC Module Specifications (see Table 29-32). Updated the 10-bit Conversion Rate Parameters and added Note 3 (see Table 29-33). Added Note 4 to the Analog-to-Digital Conversion Timing Requirements (see Table 29-34). Added Note 3 to CTMU Current Source Specifications (see Table 29-39).
30.0 “50 MHz Electrical Characteristics”	New chapter with electrical characteristics for 50 MHz devices.
31.0 “Packaging Information”	The 36-pin and 44-pin VTLA packages have been updated.

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